

ABSTRACT

Methods Of Forming Wire Bonds For Wire Loops And Conductive Bumps

A method of forming a wire bond using a wire bonding machine is provided. The method includes the steps of: (1) selecting at least one target bonding control value; (2) generating bonding parameters for forming a wire bond using an algorithm and the at least one selected target bonding control value; (3) forming a wire bond using the generated bonding parameters; (4) determining if the at least one selected target bonding control value of the formed wire bond is within a predetermined tolerance of the at least one selected target bonding control value; (5) adjusting at least one bonding adjustment value if the at least one selected target bonding control value of the formed wire bond is not within the predetermined tolerance; and (6) generating revised bonding parameters for forming a subsequent wire bond using an algorithm and the at least one adjusted bonding adjustment value.

Fig. 1A